SN54ABT374, SN74ABT374A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

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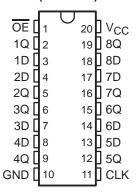
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

description

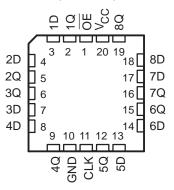
These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the SN54ABT374 and SN74ABT374A are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

SN54ABT374...J OR W PACKAGE SN74ABT374A...DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT374...FK PACKAGE (TOP VIEW)



A buffered output-enable $(\overline{\mathsf{OE}})$ input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components. \overline{OE} does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT374 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT374A is characterized for operation from -40°C to 85°C.



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EPIC-IIB is a trademark of Texas Instruments Incorporated

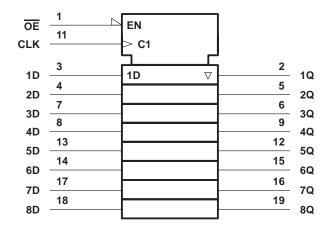


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FUNCTION TABLE (each flip-flop)

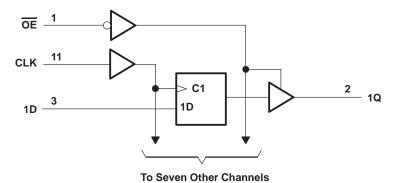
	INPUTS		OUTPUT
OE	CLK	D	Q
L	1	Н	Н
L	\uparrow	L	L
L	H or L	Χ	Q ₀
Н	Χ	Χ	Z

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SN54ABT374, SN74ABT374A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, V _I (see Note 1)		
Voltage range applied to any output in the high	or power-off state, VO	
Current into any output in the low state, IO: SN	N54ABT374	96 mA
SN	N74ABT374A	
Input clamp current, I _{IK} (V _I < 0)		–18 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Package thermal impedance, θ _{JA} (see Note 2)	: DB package	115°C/W
	DW package	97°C/W
	N package	67°C/W
	PW package	128°C/W
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54A	BT374	SN74AB	T374A	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V	
V _{IL} Low-level input voltage				0.8		0.8	V
VI	Input voltage		0	VCC	0	VCC	V
loh	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	∆v Input transition rise or fall rate Outputs enabled					5	ns/V
T _A Operating free-air temperature					-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



SN54ABT374, SN74ABT374A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEST COMPITIO	NC	Т	A = 25°C	;	SN54A	BT374	SN74AB	T374A	UNIT
PARAMETER		TEST CONDITIO	N3	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5		
Vari	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$		3			3		3		V
VOH	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$		2			2				v
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$		2*					2		
Voi	1 _{OL} = 48 mA				0.55		0.55			V	
VOL	VCC = 4.5 V	$V_{CC} = 4.5 \text{ V}$ $I_{OL} = 64 \text{ mA}$				0.55*				0.55	V
V _{hys}				100						mV	
lį	$V_{CC} = 5.5 \text{ V}, V_I = V_{CC} \text{ or GND}$					±1		±1		±1	μΑ
lozh	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$				10‡		10‡		10‡	μΑ
lozL	$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 \text{ V}$				-10‡		-10‡		−10 ‡	μΑ
l _{off}	$V_{CC} = 0$,	V_I or $V_O \le 4.5 V_O$	'			±100				±100	μΑ
ICEX	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 \text{ V}$	Outputs high			50		50		50	μΑ
ΙΟ [§]	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$		-50	-100	-180	-50	-180	-50	-180	mA
	.,	0	Outputs high			250		250		250	μΑ
Icc	V _{CC} = 5.5 V, I _C V _I = V _{CC} or GN		Outputs low			30		30		30	mA
	A - ACC OL QUAD		Outputs disabled			250		250		250	μΑ
ΔI _{CC} ¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
Ci	$V_I = 2.5 \text{ V or } 0.$	V _I = 2.5 V or 0.5 V			3.5						pF
Co	$V_0 = 2.5 \text{ V or } 0$).5 V			6.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54A	BT374		
			V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
			MIN	MAX			
f _{clock}	Clock frequency		0	150	0	150	MHz
t _W	Pulse duration	CLK high or low	3.3		3.3		ns
	Setup time before CLK↑	Data high	2		2.5		ns
tsu	Setup time before CLK1	Data low	2		2.5		115
t _h	Hold time after CLK↑	Data high or low	2		2.5		ns



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This data sheet limit may vary among suppliers.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN74AI	3T374A		
			V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
			MIN	MAX			
fclock	Clock frequency		0	150	0	150	MHz
t _W	Pulse duration	CLK high or low	3.3		3.3		ns
	Catura tima hafara CLVA	Data high	1		1		ns
t _{su}	Setup time before CLK	Setup time before CLK↑ Data low			1.9		115
th	Hold time after CLK↑	Data high or low	2.1		2.1		ns

[†]This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

				SN	54ABT3	74		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN	MAX	UNIT
		MIN TYP MAX						
f _{max}			150	200		150		MHz
t _{PLH}	CLK	Q	2.2	4.2	5.7	1.8	6.6	ns
^t PHL	OLK	Q	3.1	5.1	6.6	2.6	7.6	115
^t PZH	ŌĒ	Q	1.2	3.2	4.7	0.8	5.7	ns
t _{PZL}	OE	ų ,	2.3	4.7	6.2	1.5	7.2	115
^t PHZ	ŌĒ	Q	2.3	4.5	6.1	1.3	7.2	ns
t _{PLZ}	OE .	<u> </u>	1.9	4.5	6	1	7	113

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

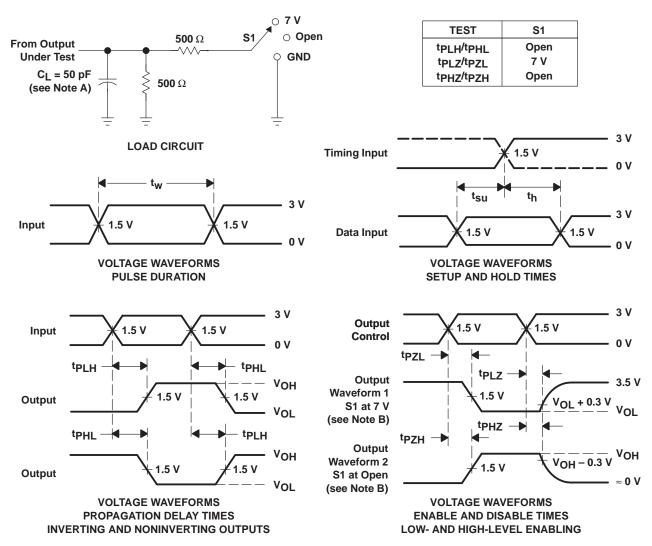
				SN7	'4ABT37	'4A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f _{max}			150	200		150		MHz
^t PLH	CLK	Q	2.2	4.2	5.7	2.2	6.2	ns
^t PHL	OLK	Q	3.1	5.1	6.6	3.1	7.1	113
^t PZH	ŌĒ	Q	1.2	3.2	4.7	1.2	5.2	ns
^t PZL	OE	ų ,	2.7	4.7	6.2	2.7	6.7	115
^t PHZ	OE	Q	2.5	4.5	6	2.5	6.7†	ne
t _{PLZ}) OE	~	2	4.5	6	2	6.5	ns

[†] This data sheet limit may vary among suppliers.



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9314901Q2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9314901Q2A SNJ54ABT 374FK
5962-9314901QRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9314901QR A SNJ54ABT374J
5962-9314901QSA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9314901QS A SNJ54ABT374W
SN74ABT374ADBR	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB374A
SN74ABT374ADBR.B	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB374A
SN74ABT374ADBRG4	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB374A
SN74ABT374ADBRG4.B	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB374A
SN74ABT374ADW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT374A
SN74ABT374ADW.B	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT374A
SN74ABT374ADWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT374A
SN74ABT374ADWR.B	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT374A
SN74ABT374ADWRE4	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT374A
SN74ABT374ADWRG4	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT374A
SN74ABT374AN	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT374AN
SN74ABT374AN.B	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT374AN
SN74ABT374ANSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT374A
SN74ABT374ANSR.B	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT374A
SN74ABT374APW	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB374A
SN74ABT374APW.B	Active	Production	TSSOP (PW) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB374A
SN74ABT374APWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB374A
SN74ABT374APWR.B	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB374A
SNJ54ABT374FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9314901Q2A SNJ54ABT 374FK

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Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SNJ54ABT374J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9314901QR A SNJ54ABT374J
SNJ54ABT374W	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9314901QS A SNJ54ABT374W

⁽¹⁾ Status: For more details on status, see our product life cycle.

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT374ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT374ADBRG4	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT374ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ABT374ANSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ABT374APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1



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*All dimensions are nominal

7 III GIII I GII GII GII GII GII GII GII							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT374ADBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74ABT374ADBRG4	SSOP	DB	20	2000	353.0	353.0	32.0
SN74ABT374ADWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74ABT374ANSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74ABT374APWR	TSSOP	PW	20	2000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9314901Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9314901QSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74ABT374ADW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT374ADW.B	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT374AN	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT374AN.B	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT374APW	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74ABT374APW.B	PW	TSSOP	20	70	530	10.2	3600	3.5
SNJ54ABT374FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ABT374W	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20







- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.







- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-150.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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